Amendments to the Claims:

The following listing replaces all prior listing of claims in the application.

Listing of Claims

1. (Currently amended) A lithographic method comprising the pressing of a substrate, the method comprising:

~~a preparation step during which~~ preparing a substrate surface ~~is covered with~~ by forming a composite layer on the substrate, wherein forming the composite layer comprises forming an internal sub-layer of curable material and curing the internal sub-layer, and forming an external sub-layer adjacent to the cured internal sub-layer;

~~a~~ pressing ~~step in which~~ a mold comprising a pattern of recesses and protrusions ~~is pressed so as to penetrate a portion of the thickness of the layer~~, wherein the protrusions of the mold penetrate into the external sub-layer until the protrusions contact the internal sub-layer;

performing at least one etching ~~step~~ process in which the composite layer is etched until ~~parts~~ portions of a surface of the substrate have been exposed; and

~~a substrate~~ etching ~~step, wherein~~ the substrate ~~is etched~~ using an etching pattern defined by the mold pattern

~~wherein the preparation step further comprises forming an internal sub-layer or curable material and curing the internal sub-layer, and forming an external sub-layer adjacent to the internal sub-layer, and~~

~~wherein the pressing step further comprises penetrating the protrusions of the mold into the external sub-layer until the protrusions contact the internal sub-layer~~.

2. (Currently amended) The method according to claim 1, wherein forming the internal sub-layer ~~is formed~~ comprises forming the internal sub-layer in contact with the substrate surface and ~~wherein, during the~~ performing at least one etching step~~,~~

comprises removing the internal sub-layer ~~is removed~~ in ~~the~~ regions defined by recesses ~~of~~ formed in the external sub-layer, and~~,~~ wherein ~~during~~ etching the substrate comprises etching ~~step,~~ regions of the substrate ~~is etched through~~ exposed by the recesses.

3. (Currently amended) The method according to claim 1, wherein forming the internal sub-layer and the external sub-layer comprise forming the same material.

4. (Currently amended) The method according to claim 1, wherein curing the internal sub-layer comprises ~~a heat treatment of~~ heating the internal sub-layer at a temperature higher than ~~its~~ a curing temperature of the internal sub-layer, and wherein ~~the~~ pressing ~~step~~ the mold comprises ~~is carried out~~ pressing at a pressing temperature higher than a glass transition temperature of the external sub-layer.

5. (Currently amended) The method according to claim 1, wherein forming the internal sub-layer of a curable material comprises forming a polymer.

6. (Currently amended) The method according to claim 1, wherein forming the internal sub-layer of a curable material comprises forming a resin ~~that is formulated~~ configured to be cross-linked.

7. (Currently amended) The method according to claim 5, wherein forming the internal sub-layer of a curable material comprises forming one of a negative resin or a positive resin.

8. (Currently amended) The method according to claim 1, wherein forming the internal sub-layer ~~has~~ comprises forming a sub-layer having a thickness of 0.01 micron to 1 micron.

9. (Currently amended) The method according to claim 1, wherein forming the external sub-layer comprises forming the ~~thickness of the~~ external sub-layer ~~is~~ to a thickness less than ~~the~~ a depth of the pattern of recesses.

10. (Currently amended) The method according to claim 6, wherein forming ~~the curable material~~ a resin comprises forming one of a negative resin or a positive resin.

11. (New) A lithographic method comprising:

forming a first layer on a substrate, the first layer comprising a curable material, and curing the first layer;

forming a second layer on the first layer, the second layer comprising a deformable material;

pressing a mold against the second layer, wherein protrusions of the mold form recesses in the second layer that expose portions of the first layer;

etching the exposed portions of the first layer using the second layer as an etch mask, and exposing surface regions of the substrate; and

etching the surface regions of the substrate.